

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 10/802,067 Application of: Jon M. Huppenthal and D. James Guzy Filed: March 16, 2004 Examiner: Chang, Daniel D. Attorney Docket No. ARB001 CON/CIP For: RECONFIGURABLE PROCESSOR MODULE COMPRISING HYBRID STACKED INTEGRATED CIRCUIT DIE ELEMENTS	Art Unit: 2819 Confirmation No.: 3775 Customer No.: 25235
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INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. § 1.97

MAIL STOP ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.97(i), please place the attached Form PTO/SB/08A of the listed non-patent publication in the above-referenced file. In submitting this reference, no representation is made or implied that the reference is or is not material to the examination of this application.

A Notice of Allowance was mailed in this case on June 26, 2006. The Issue Fee is due September 26, 2006, but has not yet been paid.

This Information Disclosure Statement is filed with no request for consideration of this reference. Accordingly, no fee is believed due. However, any fee associated herewith may be charged to Deposit Account No. 50-1123.

Respectfully submitted,

22 AUGUST 2006
Date



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